



PRICM 10

The 10th Pacific Rim International Conference on Advanced Materials and Processing

August 18-22, 2019 Xi'an, P. R. CHINA

Call for Papers (2nd Announcement)

Organized by

The Chinese Society for Metals (CSM)

Sponsored by

The Chinese Society for Metals (CSM)

The Japan Institute of Metals and Materials (JIM)

The Korean Institute of Metals and Materials (KIM)

Materials Australia (MA)

The Minerals, Metals & Materials Society (TMS)



Conference Website: www.pricm10.com



Contents / Important Dates

Contents

Invitation to PRICM10 / Conference Outline.....	2
Organizers / Committees.....	3
Symposium Organizers.....	6
Plenary Speakers.....	11
Schedule / Social Events.....	15
Call for Papers.....	16
Exhibition, Workshop & Sponsorship Opportunities.....	18
Registration / Visa Application.....	19
Conference Venue / Hotel Reservation.....	22
General Information.....	25
Access.....	26

Important Dates

- Abstract Submission Deadline
Thursday, January 31, 2019
- Manuscript (Full Paper) Submission Deadline
Wednesday, May 1, 2019
- Author's Registration Deadline
Saturday, June 15, 2019
- Early Registration Deadline (Regular Participant)
Monday, July 15, 2019
- Deadline for Cancellation
Thursday, August 1, 2019
- Registration
Sunday, August 18, 2019
- Conference (Distribution of Proceedings)
August 19-22, 2019

Invitation to PRICM10 / Conference Outline

Invitation to PRICM10

This triennial conference is the 10th in a series of international conferences devoted to advanced materials and processing. PRICM Conference is jointly sponsored by The Chinese Society for Metals (CSM), The Japan Institute of Metals and Materials (JIM), The Korean Institute of Metals and Materials (KIM), Materials Australia (MA), and The Minerals, Metals & Materials Society (TMS) and organized in rotation among these sponsoring organizations from 1992 in Hangzhou, China. The purpose of PRICM is to provide an attractive forum for the exchange of scientific and technological information on advanced materials and processing.

After 27 years, it is the third round of PRICM Conferences hosted by China. Based on the excellent performance of those previous conferences and collaborative efforts of CSM, JIM, KIM, MA and TMS, PRICM-10 will be a new leap for PRICM Conferences.

We are pleased to inform you that the conference has received a highly positive response since the first announcement. Up to now, more than 1000 delegates have been registered for this event. The exhibition and sponsorship preparations have also started and received a warm response. We welcome you all to participate in this coming major conference and to join us for exciting discussions.

Conference Outline

Date: August 18-22, 2019

Venue: Xi'an Qujiang International Conference Center

Official Language: English



Organizers / Committees

Organized by

The Chinese Society for Metals (CSM)

Sponsored by

The Chinese Society for Metals (CSM)

The Japan Institute of Metals and Materials (JIM)

The Korean Institute of Metals and Materials (KIM)

Materials Australia (MA)

The Minerals, Metals & Materials Society (TMS)

Local Co-organized by

Beihang University

Northwest Institute for Nonferrous Metal Research Group

Northwestern Polytechnical University

Xi'an Jiaotong University

Xi'an University of Architecture and Technology

Supported by

Chinese Materials Research Society

Honorary Chairman

Yuqing Weng Chinese Academy of Engineering

Conference Chairman

Huibin Xu Beihang University

In-Country Technical Representatives

CSM

Prof. Chengjia Shang, University of Science & Technology Beijing

Email: cjshang@ustb.edu.cn

JIM

Prof. Haruyuki Inui, Kyoto University

Email: inui.haruyuki.3z@kyoto-u.ac.jp

KIM

Prof. Sung-Joon Kim, POSTECH

Email: sjkim1@postech.ac.kr

MA

Prof. Jian-Feng Nie, Monash University

Email: jianfeng.nie@monash.edu

TMS

Dr. George T. Gray III, Los Alamos National Lab

Email: rusty@lanl.gov

International Organizing Committee Members

CSM

Fusheng Pan	Chongqing University
Chengjia Shang	University of Science & Technology Beijing
Zhiling Tian	Center Iron & Steel Research Institute
Weihua Wang	The Institute of Physics, Chinese Academy of Sciences
Guoqing Zhang	Beijing Institute of Aeronautical Materials
Tongyi Zhang	Shanghai University
Pei Zhao	The Chinese Society for Metals

JIM

Yoshitsugu Kojima	Hiroshima University
Nobuhiro Tsuji	Kyoto University
Satoshi Sugimoto	Tohoku University
Hideharu Nakashima	Kyushu University

KIM

Young-Chang Joo	Seoul National Univ.
Hyuck-Mo Lee	KAIST
Woo-Young Lee	Yonsei University

MA

Allan Morton	Monash University
Ming-Xing Zhang	University of Queensland
Daniel East	CSIRO

TMS

Saryu Fensin	Los Alamos National Lab
Brajendra Mishra	Metal Processing Institute (MPI)
Dan Thoma	University of Wisconsin - Madison

International Advisory Board Members

CSM	Yafang Han	Chinese Materials Research Society
	Xishan Xie	University of Science & Technology Beijing
	Zengyong Zhong	The Chinese Society for Metals
JIM	Hiroshi Fukutomi	The Open University of Japan
	Tomoyuki Kakeshita	Fukui University of Technology
	Mitsuo Niinomi	Tohoku University
KIM	Kyung Tae Hong	KIST
	Chang Hee Lee	Hanyang University
	Chong Soo Lee	POSTECH
MA	Matthew Barnett	Deakin University
	Simon Ringer	University of Sydney
	David StJohn	University of Queensland
TMS	Diran Apelian	Metal Processing Institute (MPI)
	Marc Meyers	University of California San Diego
	Robert Shull	National Institute of Standards & Tech.

Secretary General

Xinjiang Wang The Chinese Society for Metals

Symposium Organizers

A. Advanced Steels and Processing

CSM:

Han DONG

Professor of Shanghai University

Email:

donghan@cisri.com.cn, 13910077790@163.com

Zhigang YANG

Professor of Tsinghua University

Email: zgyang@tsinghua.edu.cn

JIM:

Yoshitaka ADACHI

Professor of Nagoya University

Email:

adachi.yoshitaka@material.nagoya-u.ac.jp

KIM:

Dong-Woo SUH

Professor of Pohang University of Science and Technology (POSTECH)

E-mail : dongwoo1@postech.ac.kr

MA

Christopher HUTCHINSON

Professor of Monash University

Email:

christopher.hutchinson@monash.edu

TMS

Amy CLARKE

Colorado School of Mines

Email: amyclarke@mines.edu

B. High Temperature Structural Materials

CSM:

Qiang FENG

Professor of University of Science and Technology Beijing

Email: qfeng@skl.ustb.edu.cn

Shengkai GONG

Professor of Beihang University

Email: gongsk@buaa.edu.cn

Jun ZHANG

Professor of Northwestern Polytechnical University

Email: zhjscott@nwpu.edu.cn

JIM:

Hiroyuki YASUDA

Professor of Osaka University

Email: hyyasuda@mat.eng.osaka-u.ac.jp

KIM:

Hyun Uk HONG

Professor of Changwon National University

Email: huhong@changwon.ac.kr

MA

Damon KENT

Senior Lecturer of University of Sunshine Coast

Email: dkent@usc.edu.au

TMS

Sammy TIN

Illinois Institute of Technology

Email: tin@iit.edu

Eric TALEFF

The University of Texas at Austin

Email: taleff@utexas.edu

C. Light Metals and Alloys

CSM:

Fusheng PAN

Academician, Professor of Chongqing University

Email: fspan@cqu.edu.cn

Baiqing XIONG

Professor of GRINM Group Co. Ltd.

Email: xiongbq@grinm.com

Yongqing ZHAO

Professor of Northwest Institute for Nonferrous Metal Research

Email: trc@c-nin.com

JIM:

Yoshihito KAWAMURA

Professor of Kumamoto University

Email: rivervil@gpo.kumamoto-u.ac.jp

KIM:

Young Min KIM

Principal Researcher of Korea Institute of Materials Science (KIMS)

Email: ymkim@kims.re.kr

MA
Jian-Feng NIE
Professor of Monash University
Email: jianfeng.nie@monash.edu

TMS
Diran APELIAN
Worcester Polytechnic Institute
Email: DAPELIAN@WPI.EDU

D. Advanced Processing of Materials

CSM:
Wanqi JIE
Professor of Northwestern Polytechnical University
Email: jwq@nwpu.edu.cn
Jianguo LI
Professor of Shanghai Jiaotong University
Email: lijg@sjtu.edu.cn

JIM:
Hideyuki YASUDA
Professor of Kyoto University
Email: yasuda.hideyuki.6s@kyoto-u.ac.jp

KIM:
Myoung-Gyu LEE
Professor of Seoul National University
Email: myounglee@snu.ac.kr

MA
Huijun LI
Professor of University of Wollongong
Email: huijun@uow.edu.au

TMS
Dan THOMA
University of Wisconsin- Madison
Email: dthoma@wisc.edu

E. Thin Films and Surface Engineering

CSM:
Chuang DONG
Professor of Dalian University of Technology
Email: dong@dlut.edu.cn
Hongbo GUO
Professor of Beihang University
Email: Guo.hongbo@buaa.edu.cn

JIM:
Hiroshi MASUMOTO
Professor of Tohoku University
Email: hiromasu@fris.tohoku.ac.jp

KIM:
Ho Won JANG
Professor of Seoul National University
Email: hwjang@snu.ac.kr

MA
Mingxing ZHANG
Professor of University of Queensland
Email: mingxing.zhang@uq.edu.au

F. Biomaterials

CSM:
Yufeng ZHENG
Professor of Peking University
Email: yfzheng@pku.edu.cn
Luning WANG
Professor of University of Science and Technology Beijing
Email: luning.wang@ustb.edu.cn

JIM:
Takayoshi NAKANO
Distinguished Professor of Osaka University
Email: nakano@mat.eng.osaka-u.ac.jp

KIM:
Seung-Kyun KANG
Professor of Korea Advanced Institute of Science and Technology (KAIST)
Email: skang17@kaist.ac.kr

MA
Cuie WEN
Professor of RMIT University
Email: cuie.wen@rmit.edu.au

TMS
Marc MEYERS
University of California, San Diego
Email: mameyers@eng.ucsd.edu

G. Smart and Magnetic Materials

CSM:
Shaoxiong ZHOU

Professor of Center Iron & Steel Research
Institute
Email: sxzhou@atmcn.com
Chengbao JIANG
Professor of Beihang University
Email: jiangcb@buaa.edu.cn

JIM:
Satoshi SUGIMOTO
Professor of Tohoku University
Email: sugimots@material.tohoku.ac.jp

KIM:
Haein LIM
Professor of Sookmyung Women's
University
Email: haein@sm.ac.kr

MA
Sean LI
Professor of New South Wales
Email: sean.li@unsw.edu.au

TMS
Bob SHULL
National Institute of Standards and
Technology
Email: robert.shull@nist.gov

H. Materials Characterisation and Evaluation

CSM:
Zhiwei SHAN
Professor of Xi'an Jiaotong University
Email: zwshan@mail.xjtu.edu.cn
Xiaodong HAN
Professor of Beijing University of
Technology
Email: xdhan@bjut.edu.cn

JIM:
Satoshi HATA
Professor of Kyushu University
Email: hata.satoshi.207@m.kyushu-u.ac.jp

KIM:
Ju-Young KIM
Professor of Ulsan Institute of Science and
Technology (UNIST)
Email: juyoung@unist.ac.kr

MA
Jin ZOU
Professor of University of Queensland
Email: j.zou@uq.edu.au

TMS
Jennifer CARTER
Case Western Reserve University
Email: jwc137@case.edu

I. Composite Materials

CSM:
Lin GENG
Professor of Harbin Institute of Technology
mail: genglin@hit.edu.cn
Boming ZHANG
Professor of Beihang University
Email: zbm@buaa.edu.cn

JIM:
Junya INOUE
Associate Professor of Tokyo University
Email: inoue@material.t.u-tokyo.ac.jp

KIM:
Sang Bok LEE
Principal Researcher of Korea Institute of
Materials Science (KIMS)
Email: leesb@kims.re.kr

MA
Hao WANG
Professor of University of Southern
Queensland
Email: Hao.Wang@usq.edu.au

TMS
Rusty Gray III
Los Alamos National Lab
Email: rusty@lanl.gov

J. Amorphous Alloy and High Entropy Alloys

CSM:
Weihua WANG
Academician, Professor of The Institute of
Physics, Chinese Academy of Sciences
Email: whw@iphy.ac.cn
Zhaoping LV
Professor of University of Science and
Technology Beijing

Email:luzp@ustb.edu.cn

JIM:

Hidemi KATO
Professor of Tohoku University
Email: hikato@imr.tohoku.ac.jp

KIM:

Hojin RYU
Professor of Korea Advanced Institute of
Science and Technology (KAIST)
Email: hojinryu@kaist.ac.kr

MA

Michael FERRY
Professor of New South Wales
Email: m.ferry@unsw.edu.au
TMS
Evan MA
Johns Hopkins University
Email: ema.mse.jhu@gmail.com

K. Nanocrystalline and Ultrafine-Grained Materials

CSM:

Yue ZHANG
Professor of University of Science and
Technology Beijing
Email: yuezhang@ustb.edu.cn
Zhiyong TANG
Professor of National Center for
Nanoscience and Technology
Email: zytang@nanoctr.cn

JIM:

Nobuhiro TSUJI
Professor of Kyoto University
Email: nobuhiro-tsuji@mtl.kyoto-u.ac.jp

KIM:

Jae-il JANG
Professor of Hanyang University
Email: jijang@hanyang.ac.kr

MA

Kenong XIA
Professor of University of Melbourne
Email: k.xia@unimelb.edu.au

TMS

Nathan Mara

University of Minnesota

Email: mara@umn.edu

L. Computational Design and Simulation of Materials

CSM:

Tongyi ZHANG
Academician, Professor of Shanghai
University
Email: zhangty@shu.edu.cn
Zhimei SUN
Professor of Beihang University
Email: zmsun@buaa.edu.cn

JIM:

Shigenobu OGATA
Professor of Osaka University
Email: ogata@me.es.osaka-u.ac.jp

KIM:

Byeong-Joo LEE
Professor of Pohang University of Science
and Technology (POSTECH)
E-mail : calphad@postech.ac.kr

MA

Salvy RUSSO
Professor of RMIT
Email: salvy.russo@rmit.edu.au

TMS

Saryu FENSIN
Los Alamos National Lab
Email: saryuj@lanl.gov
Michele MANUEL
University of Florida
Email:

M. Renewable Energy Materials and Nuclear Materials

CSM:

Min ZHU
Professor of South China University of
Technology
Email: memzhu@scut.edu.cn
Yuan DENG
Professor of Beihang University
Email: dengyuan@buaa.edu.cn
Guanghong LU
Professor of Beihang University
Email: LGH@buaa.edu.cn

JIM:
Tetsuya UDA
Professor of Kyoto University
Email: uda.tetsuya.5e@kyoto-u.ac.jp

KIM:
Taek-Soo KIM
Principal Researcher of Korea Institute of
Industrial Technology (KITECH)
Email: tskim@kitech.re.kr

MA
Dmitri GOLBERG
Professor of Queensland University of
Technology
Email: dmitry.golberg@qut.edu.au

TMS
Assel AITKALIYEVA
University of Florida
Email: aitkaliyeva@mse.ufl.edu

N. Additive Manufacturing and Powder Metallurgy

CSM:
Huiping TANG
Professor of Northwest Institute for
Nonferrous Metal Research
Email: hptang@c-nin.com
Yong LIU
Professor of Central South University
Email: yonliu@mail.csu.edu.cn

JIM:
Yuichiro KOIZUMI
Professor of Osaka University
Email: ykoizumi@mat.eng.osaka-u.ac.jp

KIM:
Kee-Ahn LEE

Professor of Inha University
Email: keeahn@inha.ac.kr

MA
Qian MA
Professor of RMIT
Email: ma.qian@rmit.edu.au

TMS
Ed HERDERICK
Ohio State University
Email: herderick.2@osu.edu

O. Electronic and Spin Electron Materials

CSM:
Hongda CHEN
Professor of Institute of Semiconductors,
Chinese Academy of Sciences
Email: hdchen@semi.ac.cn
Feng PAN
Professor of Tsinghua University
Email: panf@mail.tsinghua.edu.cn

JIM:
Rie Y. UMETSU (Ms.)
Associate Professor of Tohoku University
Email: rieume@imr.tohoku.ac.jp

KIM:
Joon Yeon JANG
Principal Researcher of Korea Institute of
Science and Technology (KIST)
Email: presto@kist.re.kr

MA
Lianzhou WANG
Professor of University of Queensland
Email: l.wang@uq.edu.au

Plenary Speakers

CSM

Bingbo WEI

Academician, President of Chinese Materials Research Society
Professor of Northwestern Polytechnical University

Presentation Title: Recent Progress in Space Materials Science and Technology

Bingbo Wei, born in April 1964 at Shandong province of China, professor of materials science at the department of applied physics in Northwestern Polytechnical University (NPU), member of Chinese Academy of Sciences, president of Chinese Materials Research Society. He graduated from the mechanical engineering department of Shandong Engineering Institute and got a BE degree for foundry technology in 1983. Obtained a ME degree for solidification technology in 1986 at the materials science department of Nanjing Institute of Technology. In 1989, he received a Ph.D degree for rapid solidification research at department of materials science and engineering in NPU. After his doctoral study, he became lecturer of physical metallurgy at NPU and got involved in China's early programs of space science research. With the supports of Alexander von Humboldt Foundation, he went to German Aerospace Research Center, Max-Planck-Institute of Metals Research and Swiss Federal Institute of Technology Lausanne for cooperative investigations in the two years of 1991-1992. Promoted to professor of materials science at NPU in 1992 and appointed as director of applied physics department in 1998. He was the founding director of Ministerial Key Laboratory for Space Materials Science and Technology and the founding dean of School for Natural and Applied Sciences in NPU. In the respect of university administration, he served as the vice president for scientific research (2007-2013) and graduate education (2014-2018) of NPU. His research subjects include the directional solidification of aluminum alloys, rapid solidification of superalloys, containerless processing of refractory alloys, thermophysical properties of undercooled liquid alloys, and space materials science and technology. He was elected to Chinese Academy of Sciences in 2011. Served as the vice president of Chinese Materials Research Society for the 10 years of 2007-2017 and became the president in 2018.



JIM



Mitsuo NIINOMI

Presentation Title: Research and Development of Metallic Biomaterials for Inhibiting Stress-shielding between Implant and Bone

Honorary Professor of Tohoku University

Visiting Professor of Tohoku University

Specially Appointed Professor of Osaka University

Specially Appointed Professor of Meijo University

Visiting Professor of Nagoya University

KIM



Hyung Seop KIM

Pohang University of Science and Technology (POSTECH), Korea

Presentation Title: Design, Properties, and Applications of High Entropy Alloys

Professor Hyung Seop Kim of POSTECH got his bachelor (1986), master (1988), and Ph.D. (1992) degrees in department of metallurgical engineering, Seoul National University, spent in Chungnam National University (1995-2008), and has joined department of materials science and engineering and graduate institute for ferrous technology (GIFT). POSTECH in 2008. He is the director of the Center for High Entropy Alloys, supported by the Future Materials Discovery Program of Korean National Research Foundation. He was the British Council Fellow (University of Oxford, 1997-1998), Australian Research Council Fellow (The university of Western Australia, 1988-1999), DAAD Scholar (TU Clausthal, 2001), British Chevening Scholar (University of Oxford, 2001-2002). JSPS Fellow (Tohoku University, 2003; Kyushu University, 2007), DFG Visiting Fellow (TU Clausthal, 2004), Visiting Professor (University of

Pennsylvania, 2005-2007, 2015-2016). He is the editor-in-chief of *Metals and Materials International*, editor of *Materials Research Letters*, associate editor of *Science and Technology of Advanced Materials*, and editorial board member of *Materials Science and Engineering A* and *Journal of Materials Science*. He has published more than 500 SCI papers (citations over 7000, h-index 43, Clarivate Analytics). His research field is microstructure and mechanism-based plasticity theory and its application to advanced materials (e.g. porous, amorphous, ultrafine grained, nanocrystalline, heterogeneous metallic materials) and processing (powder metallurgy, severe plastic deformation, additive manufacturing, and material architecturing). He is the Fellow of both the Korean Academy of Science and Technology and the National Academy of Engineering of Korea.

MA

Joanne ETHERIDGE

Monash University, Australia

Presentation Title: Finding the atoms that matter in functional materials



Joanne Etheridge is the founding Director of the Monash Centre for Electron Microscopy and Professor in the Department of Materials Science and Engineering at Monash University. She obtained her degree and PhD in physics at the University of Melbourne and RMIT University, respectively. She then held appointments at the University of Cambridge in the Department of Materials Science and Metallurgy and Newnham College, including a Rosalind Franklin Research Fellowship and a Royal Society University Research Fellowship. She returned to Melbourne to join Monash University where she established the Monash Centre for Electron Microscopy. She conducts research in the theory and development of new electron scattering methods for determining the atomic and electronic structure of condensed matter. She also applies these methods to the study of structure-property relationships in functional materials, including plasmonic nanoparticle systems, photoactive and ion-conducting perovskite-based systems, functional oxides and semiconductor systems.

Kevin HEMKER

Johns Hopkins University, USA

Presentation Title: Understanding and Developing Nanostructured Materials with Requisite Properties and Stability

Kevin Hemker is the Alonzo G. Decker Chair and Professor of Mechanical Engineering at Johns Hopkins University and holds joint appointments in the Departments of Materials Science & Engineering and Earth & Planetary Sciences. He earned a BS in metallurgy from the University of Cincinnati, MS and PhD degrees in materials science and engineering from Stanford University, and completed a postdoctoral fellowship in physics at the Ecole Polytechnique Federale de Lausanne. He joined the faculty at Johns Hopkins University in 1993, was an NSF National Young Investigator (1994), an invited Professor at the EPFL (1995) and the University of Paris XIII (2001), and received the ASM Materials Science Research Silver Medal in 2001. He served as Chair of the Department of Mechanical Engineering (2007-2013) and editor of Scripta Materialia (2004-2011). He was a member and Vice-Chair of the DARPA Defense Science Research Council (2010-2014), and is currently a member of the HRL Technical Advisory Group, the SRI Technology Council and President of The Minerals, Metals, Materials Society (TMS). Hemker has been named Fellow of AAAS, ASME, ASM International and TMS.



Hemker has mentored approximately 75 postdoctoral fellows, doctoral and masters students since coming to Hopkins, more than 15 of whom now have tenured or tenure-track academic positions in major research universities (U Penn, UIUC, UCSB, Tohoku U, U Freiburg, TAMU, etc.). His group strives to elucidate the underlying atomic-level details that govern the mechanical response, performance and reliability of disparate material systems. They have made key observations and discoveries that have challenged the way the community thinks about and understands materials behavior in: additive manufacturing, nanocrystalline materials, materials for MEMS, metallic micro-lattices, thermal barrier coatings for satellites and gas turbines, armor ceramics, extreme environments, and high temperature structural materials in general. The results of their research have been disseminated in approximately 250 scientific articles, 4 co-edited books and over 300 invited presentations and plenary lectures.

Schedule / Social Events

Schedule

Date	Activity		
	<i>Morning</i>	<i>Afternoon</i>	<i>Evening</i>
August 18, Sunday	—	Registration	Registration Welcome Party
August 19, Monday	Plenary Session	Parallel Sessions	—
August 20, Tuesday	Parallel Sessions	Parallel Sessions	—
August 21, Wednesday	Parallel Sessions	Parallel Sessions	Banquet
August 22, Thursday	Parallel Sessions	Parallel Sessions	—
Conference Venue: Qujiang International Conference Center			

Social Events

Welcome Party

Sunday, August 18 / Evening

Venue: Qujiang International Conference Center

All registered regular authors and participants are invited to attend the Welcome Party free of charge.

A light meal and drinks will be served.

Banquet

Wednesday, August 21 / Evening

Venue: Qujiang International Conference Center

All registered regular authors and participants are invited to attend the Banquet free of charge.

Call for Papers

Abstract Submission

All contributions on the topics of the Conference as described previously are welcomed. Prospective authors are invited to submit an abstract (300 words in English), the deadline of for abstract submission is **January 31, 2019**. The abstracts are requested to submit through the conference website: www.pricm10.com. If there are any problems during the submission process, please contact the Conference Secretariat (email: pricm10@csm.org.cn).

Manuscripts

The manuscripts are requested to submit through the conference website before **May 1, 2019**. Please submit the documents both in MS Word and PDF format. Please download the authors guide for manuscript and copyright transfer form from the conference website (www.pricm10.com).

Publication

All the accepted papers will be published in the conference proceedings which will not be released to the public. The technical program including abstracts will be printed in hard-copy form, and handed out to all participants upon registration.

According to the suggestions of organizing committee, only manuscripts could be chosen as the keynote and invited papers. Meanwhile, a selection of the best manuscripts will be recommended to the following journals (updated):

No.	Source of Papers	Journal	Index
1	Plenary Lectures Keynote Papers	SCIENCE CHINA Materials	SCI, EI, etc.
2	Plenary Lectures Keynote Papers Symposium B Symposium H	Progress in Natural Science: Materials International	SCI, etc.

3	Plenary Lectures Keynote Papers	Acta Metallurgica Sinica	SCI, EI, etc.
4	Plenary Lectures Keynote Papers Symposium B	Journal of Rare Earths	SCI, EI, etc.
5	Plenary Lectures Keynote Papers	Journal of Iron and Steel Research International	SCI, EI
6	Plenary Lectures Keynote Papers	Chinese Journal of Mechanical Engineering	SCI
7	Symposium F	Bioactive Materials	ESCI,PMC, Scopus, EMBASE
8	Symposium C: Magnesium	Journal of Magnesium and Alloys	SCI
9	Symposium I	Composites Communications	ESCI, etc.

Presentation

- ✧ Authors could choose the type of presentation (oral or poster) in the registration. The final result will be given to the author after the paper is reviewed by experts.
- ✧ Each presentation could be arranged in the technical program only if at least one author's registration fee is paid before **June 15, 2019**.

Poster Award

Poster Award for Young Scientist will be presented to the excellent poster submitted by young scientist under the age of 30.

Exhibition, Workshop & Sponsorship Opportunities

As the integral elements of the event, PRICM10 will feature the exhibition and workshop that will enable excellent exposure for company products, technologies, innovative solutions or services. The exhibition and workshop will be organized near the meeting room during PRICM10. The conference will offer an excellent opportunity for companies to do business and maintain key contacts with customers and suppliers. It is also a unique platform for them to promote new products, outline services and highlight key achievements.

Companies will be able to reinforce their participation and enhance their corporate identification by taking advantage of the benefits offered to them as sponsors of the conference.

If you would like to join the exhibition, workshop or sponsorship, please contact with the Conference Secretariat .

Exhibition Condition

The exhibition booth will be located near to the venue of PRICM10, the rent rate and booth size is Standard Booth: 3 × 3 (m²)

Standard booth will be provided: three-side wooden walls, one information desk, two chairs, two lights, one power outlet (220V) and company's name panel.

1. Exhibitors who wish to participate in the event please fill in Reservation form.
2. Exhibition booth arrangement: Due to venue constraints, the total number of booths is limited.

Booth will be arranged and confirmed based on the sequence of enrollment and payment successively.

Workshop

The workshops will be held in Xi'an Qujiang International Conference Center from 14:00 to 17:00 on 18 August 2019. Companies are welcome to demonstrate their products, equipment, new technologies and manufacturing processes.

✧ **CNY 18000/1 hour**

Registration / Visa Application

Registration

- ✧ Registration Deadline for Authors June 15, 2019
- ✧ Early Registration Deadline for Participants July 15, 2019

Fees

Authors

- ✧ **CNY 5300 (Regular)** **CNY 2800 (Student)**

*Notes: 1) Each accepted paper will be published in the conference proceedings only if at least one author's registration fee is paid before **June 15, 2019**.

2) Oral or poster presentation will be arranged only if at least one author's registration fee is paid before **June 15, 2019**.

3) Students are requested to submit the copy of their student ID.

Participants

Registration Fee	Before July 15, 2019	After July 15, 2019 before August 5, 2019	On August 18, 2019
Regular Participants	CNY 5500	CNY 5700	CNY 5900
Students	CNY 3000	CNY 3200	CNY 3400

**Note: Students are requested to submit the copy of their student ID*

Entitlement

Registration Fee for regular participants covers:

Conference fee, All official documentation (technical program book, conference proceedings, etc.), Welcome Reception, Banquet, Tea/Coffee Break, Lunch buffet during the conference, Name badge

Registration fee for students covers:

Conference fee, All official documentation (technical program book, conference proceedings, etc.), Tea/Coffee Break, Lunch buffet during the conference, Name badge

Method of Payment

1. Online Payment

Through the conference online payment , all payments could be made in CNY by credit card.

2. Bank Transfer

Please transfer the registration fee to the following bank account, and specify with "PRICM10, Registration No.". A copy of remittance certificate is requested to send to the conference secretariat or submit to the conference website.

Name of Bank	INDUSTRIAL AND COMMERCIAL BANK OF CHINA BEIJING MUNICIPAL BRANCH WANG FU JING SUB-BRANCH OFFICE
Beneficiary and Account Holder	The Chinese Society for Metals
Address	NO.237 WANG FU JING STREET, DONG CHENG DISTRICT, BEIJING 100006 P.R.CHINA
SWIFT ADDRESS	ICBKCNBJBJM
Account Number	0200000709089116848

*Notes: 1) The Check will not be accepted

2) The registration fee doesn't include the bank charge.

3) The receipt will be provided at the registration desk during the conference.

3. Payment in CNY at the Registration Desk

Attendees are requested to pay by credit card in CNY on the registration day.

Cancellation

Refunds cannot be given if cancellations received after August 1, 2019. Substitutions can be accepted at any time.

Please indicate the bank, branch and account number clearly to which the refund should be sent, and the refund will be made after the conference.

Cancellation	Refund
Before August 1, 2019	80%
After August 1, 2019	No refund (Conference proceedings will be sent to the authors after the conference)

Visa Application

People from most countries will be required to obtain a visa to enter the People's Republic of China. PRICM10 participants who are required to apply for visa to enter China can apply for a Chinese visa at the nearest Embassy or Consulate of China in your countries. For some visa applications, the process could take some time to complete, depending on your country of origin and certain visa restrictions so we would like to suggest you start the visa application as early as possible.

As conference hosts, we can issue you an invitation letter for your visa with the necessary signature and official stamp. If you need, please log in your account and download it in “My Page” after paying for your registration.

Tips: Local organizers could NOT provide conference invitation letter to accompanying personnel according to related regulations. We suggest that accompanying personnel apply for tourism type visa, which will be much easier and require less paperwork.

For example, if you apply for visa at New York, firstly need check website of the local Consulate General of China for updated info at:

<http://newyork.china-consulate.org/eng/lsw/lzjx/sbqz/fptp/>

When you fill out the visa application form, in “Part 2.1 Major purpose of your visit”, you could select “Tourism”. In “Part 2.2 Intended number of entries”, you could select “Other:” and fill out “Multiple entries for 10 years”. This will cost you same amount of application fee as apply for “Single entry for 3 months”.

Notes:

1. The invitation letter could be issued after May 1, 2019. According to the conference time, the entry date of the invitation letter will start from August 16.
2. You should guarantee that all information provided is true and correct.
3. In the letter for visa, we can only guarantee your stay in Xi'an during congress period.
4. General visa information should be obtained from your local Embassy or Consulate of China. You could also check the information from <http://www.visaforchina.org/>

Conference Venue / Hotel Reservation

Conference Venue

The conference will be held in Xi'an Qujiang International Conference Center (QICEG) from August 18-22, 2019. QICEG is ideally located in the heart of Xi'an city adjacent to The Dayan Pagoda, Daci'en Temple, and which is next to the "Hui Zhan Zhong Xin (会展中心)" Station of subway line 2.

Accommodation

For the participants of PRICM10, the special rates will be effective from August 18-22, 2019. The recommended hotels and room rate are as follows:

Hotel **1. Renaissance Xi'an Hotel(西安万丽酒店)★★★★★**

Room Type Standard Room (Twin beds/King bed)

Room Rate 820CNY / 770CNY (Including Breakfast)

Network Free WIFI

Introduction Renaissance Xi'an Hotel is only 5 minutes walking distance from the "Qujiang International Conference Center".

Booking [Click here for booking](#)

Contact Ms.Gou Qianqian E-mail: catherine@kailimice.cn

Hotel **2. Ramada Plaza Xi'an South(西安曲江华美达广场酒店)★★★★★**

Room Type Standard Room (Twin beds/King bed)

Room Rate 600CNY (Including Breakfast)

Network Free WIFI

Introduction Ramada Plaza Hotel is only 5 minutes walking distance from the "Qujiang International Conference Center".

Booking [Click here for booking](#)

Contact Ms.Gou Qianqian E-mail: catherine@kailimice.cn

Hotel **3. Tianyu Fields International Hotel (天宇菲尔德国际大酒店)★★★★★**

Room Type Standard Room (Twin beds/King bed)

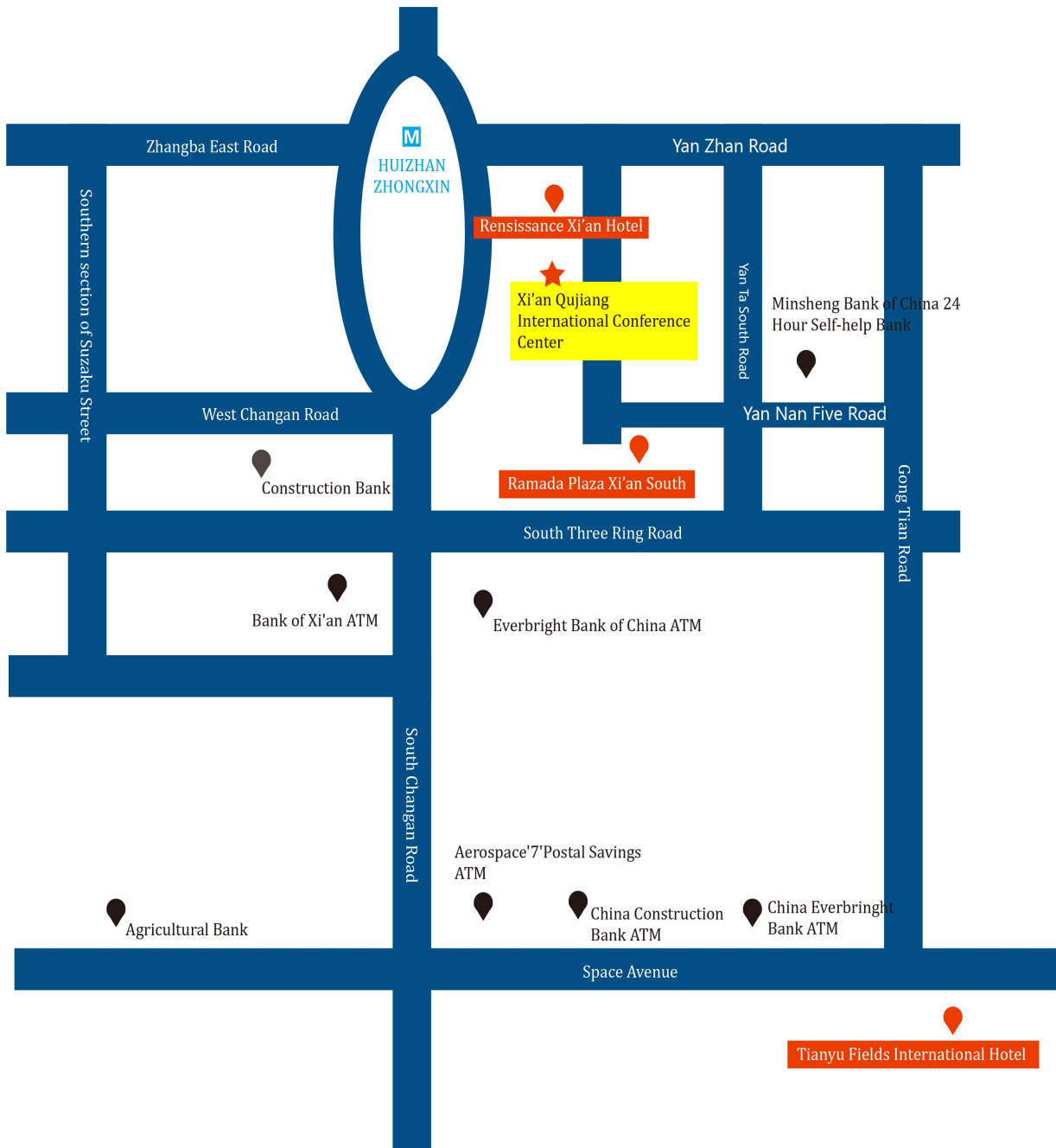
Room Rate 460CNY / 520CNY (Including Breakfast)

Network Free WIFI

Introduction Tianyu fields International Hotel is 5 km from the "Qujiang International Conference Center".

Booking [Click here for booking](#)

Contact Ms.Gou Qianqian E-mail: catherine@kailimice.cn



General Information

General Information

Climate and Clothing

During August, the average temperature in Xi'an 21-31°C.

Currency

Only CNY is acceptable at regular store and restaurants. Foreign currency or traveler's checks can be change into CNY at major banks, hotels and airports.

Credit Cards

Credit cards are widely accepted. Commonly recognized cards include Visa and MasterCard.

Tipping

There is no custom of tipping anywhere in China, even at hotels and restaurants. On certain occasions, however, a service charge is added to the bill.

Electrical Appliances

The voltage in China is 220 volts for electrical appliances. Electrical sockets usually accept two-pronged (vertical) plugs and three-pronged (vertical) plugs.

Insurance

The organizer cannot accept responsibility for accidents which might occur. It is recommended that participants take out adequate medical, travel and personal insurance prior to the commencement of travel.

Contact (about the conference)

Prof. Qing SONG, Mr. Xin ZHAO, Ms. Fang LIU

The Chinese Society for Metals

76 Xueyuan Nanlu, Beijing 100081, China

Tel: +86-10-65211205

Fax: +86-10-65124122

E-mail: pricm10@csm.org.cn

Access



Access from the nearest stations

Line 1: From XI'AN North Railway Station

Please take the subway line 1 to Hui Zhan Zhong Xin (会展中心) station, and then walk from Exit C to Qujiang International Conference Center.

Line 2: From XI'AN Railway Station

Please take the subway line 1 to Beidajie (北大街) station, and then transfer to Hui Zhan Zhong Xin (会展中心) station of subway line 2, walk from Exit C to Qujiang International Conference Center.

Access by air

From Xi'an Xianyang International Airport

➤ 110-120 minutes by shuttle bus

Please take the airport shuttle bus to Ramada Plaza Xi'an South Hotel, and walk 150 meters to Qujiang International Conference Center.

- 50-60 minutes by taxi

Please show Taxi drivers the following note for your convenience to the conference venue.

Please take me to Xi'an Qujiang International Conference Center. Thank you!

请送我到西安曲江国际会议中心

(地址: 西安市曲江新区汇新路 15 号; 电话: +86-29-87655888)